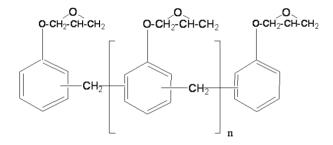
Technical Data Sheet

KEP-1138 Phenol Novolac Epoxy

General Description

The phenol novolac epoxy resin KEP-1138 is a semi-solid novolac epoxy resin. KEP-1138 has multi-functional epoxy groups which exhibit good adhesion strength, excellent heat and chemical resistance at fully crosslinked. The thermal stability offered by KEP-1138 is widely accepted as set in prepreg manufacture for electrical laminates where they improve the resistance to hot solder as well as elevated temperature service.

Chemical Structure



Resin Properties

Property	Typical values
EEW(g/eq)	170~190
Viscosity(G)*1	H~K
Hy-CI(ppm)	500 max.
Color(G)	3 max.

*1 Gardner Hodlt Method, Butyl Carbitol N.V. 60% Solution

<u>Usage</u>

- 1. Carbon fiber prepreg laminate
- 2. Electronic encapsulation and transfer molding
- 3. Electrical heat resistance molding compound
- 4. Lead free type CCL laminate varnish additives
- 5. High temperature adhesives and structural composites
- 6. Tooling, casting & molding compounds

Storage

Keep in cool, dry, ventilate condition and in closed containers.

Keep away from heat sources and direct sunlight. Recommended safe handing procedures are discussed in the information on the MSDS should reviewed and understood before working.

Packaging

Drum of 200 kg net weight

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